

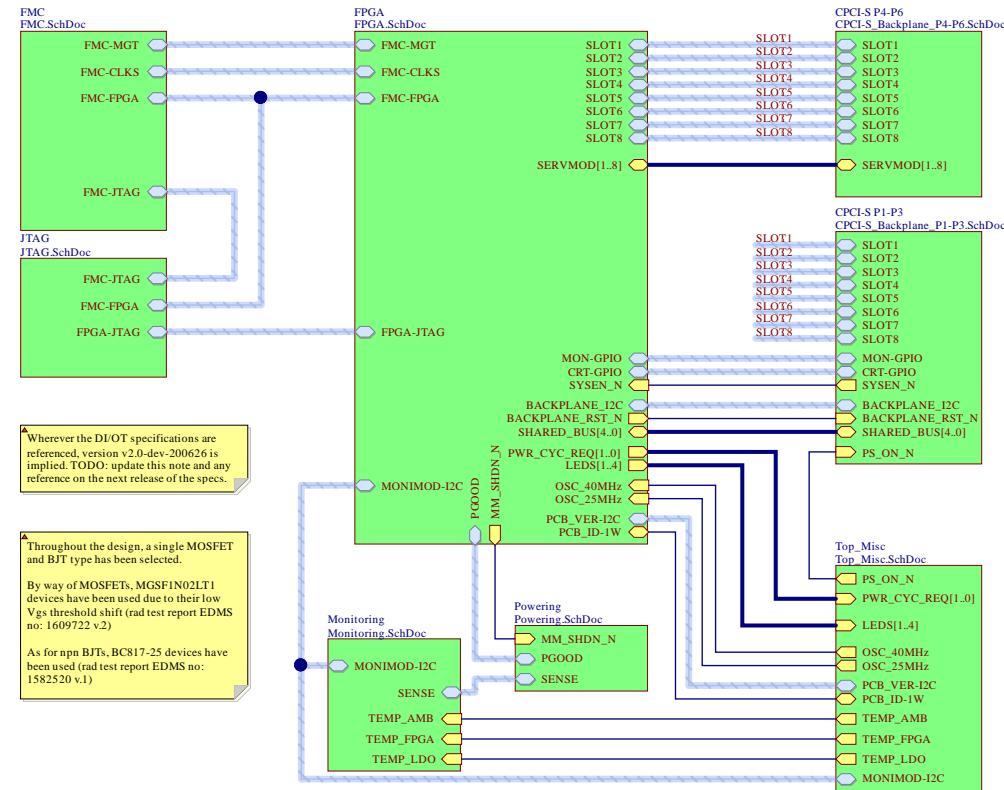
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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Project/Equipment DI/OT

Document BE/CO



DI/OT Rad-tol System Board Top Level

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

A3 | Rev *

Sheet 1 of 17

Size *

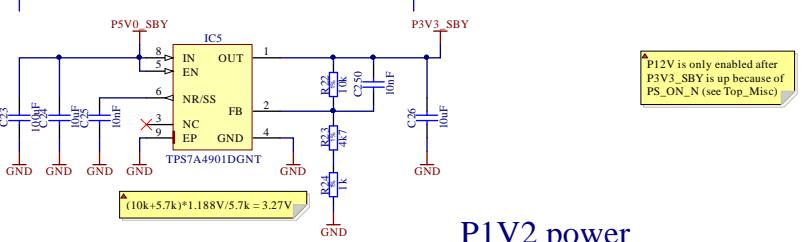
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Always-on P3V3 power



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A

A

B

B

C

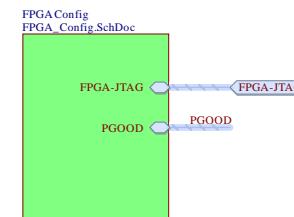
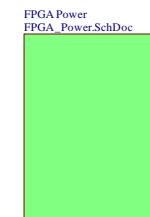
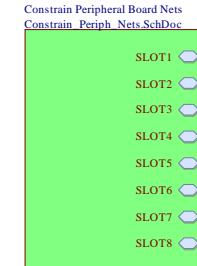
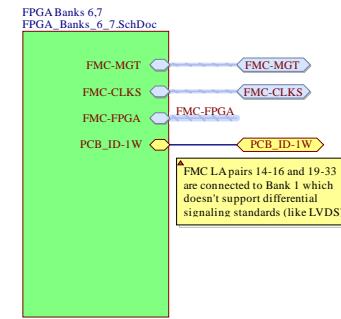
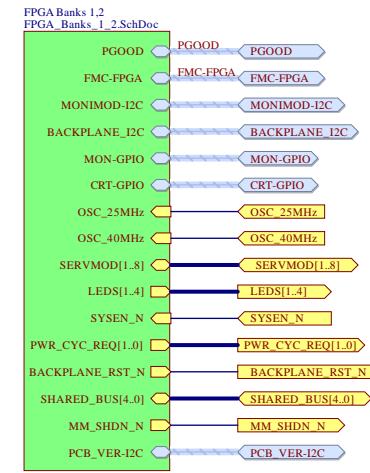
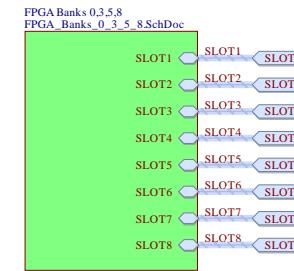
C

D

D

E

E



Project/Equipment DI/OT



**DI/OT Rad-tol System Board
FPGA Top**

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

Designer	C. Gentos	28/08/2020
Drawn by	C. Gentos	
Check by	*	
Last Mod.	C. Gentos	16/11/2020
File	FPGA.SchDoc	
Print Date	16/11/2020 16:33:29	Sheet 3 of 17
Size	A3	Rev *

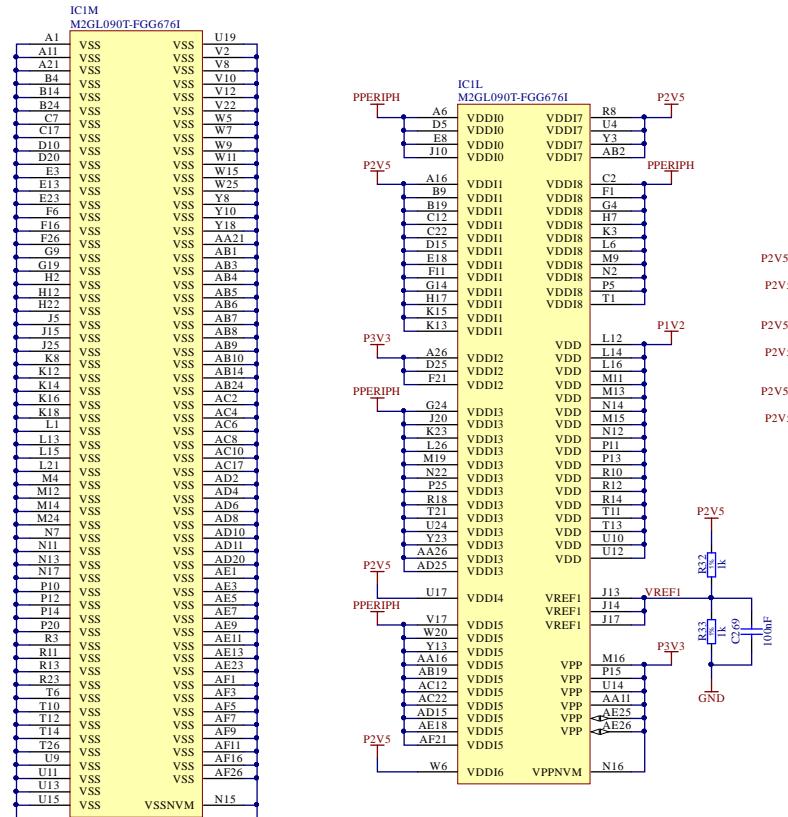
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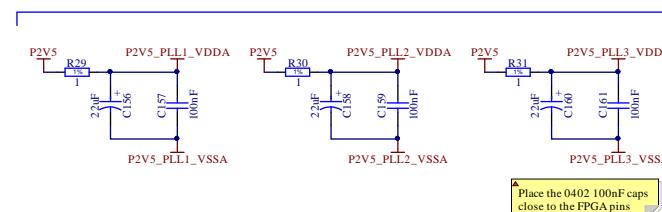
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Source location: <https://www.ohwr.org/project/diot-sb-ig>

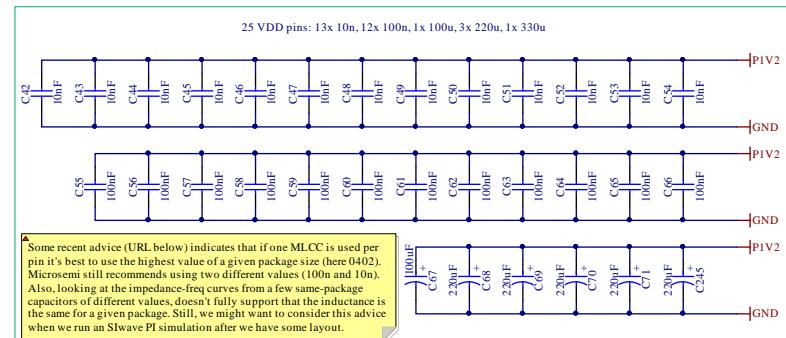
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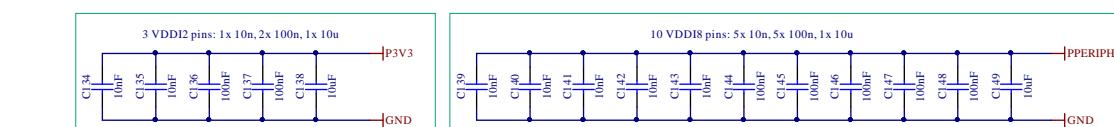
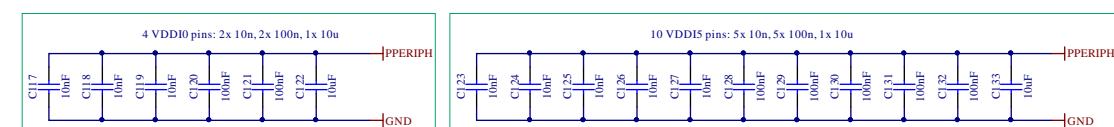
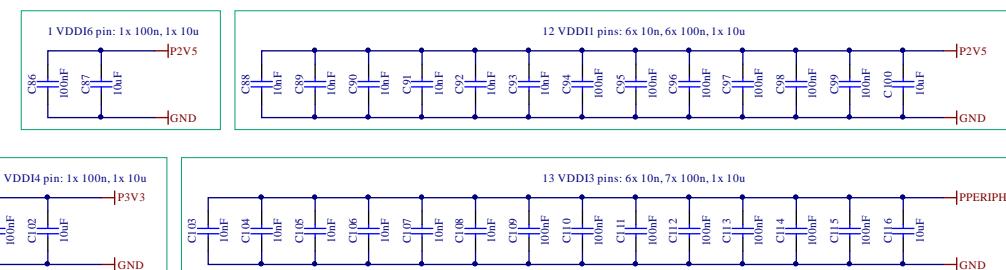
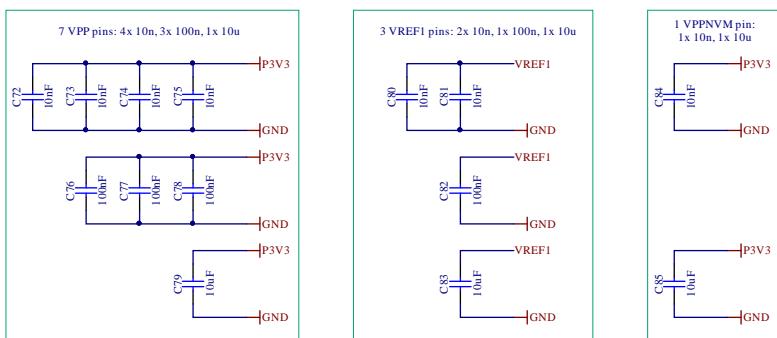
PLL RC filter



Place the 0402 100nF caps close to the FPGA pins



Some recent advice (URL below) indicates that if one MLCC is used per pin it's best to use the highest value of a given package size (here 0402). Microsemi still recommends using two different values (100n and 10n). Also, looking at the impedance-freq curves from a few same-package capacitors of different values, doesn't fully support that the inductance is the same for a given package. Still, we might want to consider this advice when we run an Siwave PI simulation after we have some layout.



Project/Equipment	DI/OT
Document	DI/OT Rad-tol System Board FPGA Power
BE/CO	Designer: C. Gentsos Drawn by: C. Gentsos Check by: * Last Mod: C. Gentsos File: FPGA_Power.SchDoc Print Date: 16/11/2020 16:33:29
CERN	Sheet 4 of 17 80x A3
European Organization for Nuclear Research CH-1211 Geneva 23 - Switzerland	EDA-XXXXX-VX-X

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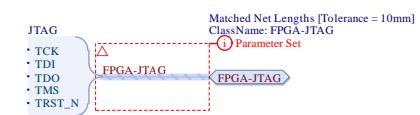
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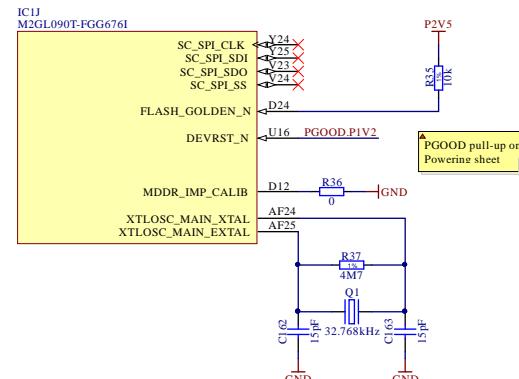
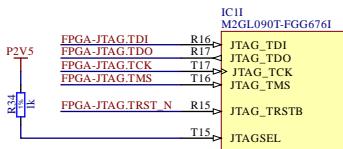
Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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Parts powered by 2.5V



The JTAG and configuration pins are referred to as Bank 4



Project/Equipment	DI/OT
Document	
BE/CO	
	DI/OT Rad-tol System Board
	FPGA Configuration and reset
CERN	
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland	Sheet 5 of 17
Print Date 16/11/2020 16:33:30	Size A3 Rev *
	EDA-XXXXX-VX-X

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Banks powered by PPERIPH

PERIPH_CONN

- LVDS_0_P
- LVDS_0_N
- LVDS_1_P
- LVDS_1_N
- LVDS_2_P
- LVDS_2_N
- LVDS_3_P
- LVDS_3_N
- LVDS_4_P
- LVDS_4_N
- LVDS_5_P
- LVDS_5_N
- LVDS_6_P
- LVDS_6_N
- LVDS_7_P
- LVDS_7_N
- LVDS_8_P
- LVDS_8_N
- LVDS_9_P
- LVDS_9_N
- LVDS_10_P
- LVDS_10_N
- LVDS_11_P
- LVDS_11_N
- LVDS_12_P
- LVDS_12_N
- LVDS_13_P
- LVDS_13_N
- LVDS_14_P
- LVDS_14_N
- LVDS_15_P
- LVDS_15_N
- LVDS_16_P
- LVDS_16_N
- LVDS_17_P
- LVDS_17_N

Intra-diff pair rule. Inter-diff pair rules can be found on a dedicated sheet.

Matched Net Lengths [Tolerance = 2mm]
 Class Name: PERIPH_DP

IC1G M2GL090T-FGG6761

BANK 8

MSIO126NBS	G7	SLOT6.LVDS_14_N
MSIO126PB8	H8	SLOT6.LVDS_14_P
MSIO127NBS	H6	SLOT6.LVDS_15_N
MSIO127PB8	H5	SLOT6.LVDS_15_P
MSIO128NBS	H7	SLOT6.LVDS_16_N
MSIO128PB8	H6	SLOT6.LVDS_16_P
MSIO129NBS	G6	SLOT6.LVDS_17_N
MSIO131NBS	G5	SLOT6.LVDS_17_P
MSIO131PB8	G4	SLOT7.LVDS_1_N
MSIO132NBS	G3	SLOT7.LVDS_2_N
MSIO132PB8	G2	SLOT7.LVDS_2_P
MSIO133NBS	G1	SLOT7.LVDS_3_N
MSIO133PB8	G0	SLOT7.LVDS_3_P
MSIO134NBS	F3	SLOT7.LVDS_4_N
MSIO134PB8	F2	SLOT7.LVDS_4_P
MSIO135NBS	F4	SLOT7.LVDS_5_N
MSIO135PB8	F3	SLOT7.LVDS_5_P
MSIO136NBS	F5	SLOT7.LVDS_6_N
MSIO136PB8	F4	SLOT7.LVDS_6_P
MSIO137NBS	F9	SLOT7.LVDS_7_N
MSIO137PB8	F8	SLOT7.LVDS_7_P
MSIO138NBS	A3	SLOT7.LVDS_8_N
MSIO138PB8	A2	SLOT7.LVDS_8_P
MSIO139NBS	K9	SLOT7.LVDS_9_N
MSIO139PB8	K10	SLOT7.LVDS_9_P
MSIO140NBS	B2	SLOT7.LVDS_10_N
MSIO140PB8	B1	SLOT7.LVDS_10_P
MSIO142NBS	J10	SLOT7.LVDS_11_N
MSIO142PB8	J9	SLOT7.LVDS_11_P
MSIO143NBS	J4	SLOT7.LVDS_12_N
MSIO143PB8	J3	SLOT7.LVDS_12_P
MSIO145NBS	K7	SLOT7.LVDS_13_N
MSIO145PB8	K6	SLOT7.LVDS_13_P
MSIO146NBS	K5	SLOT7.LVDS_14_N
MSIO146PB8	K4	SLOT7.LVDS_14_P
MSIO147NBS	M8	SLOT7.LVDS_15_N
MSIO147PB8	D2	SLOT7.LVDS_16_N
MSIO148NBS	C1	SLOT7.LVDS_16_P
MSIO148PB8	E3	SLOT7.LVDS_17_N
MSIO149NBS	D1	SLOT7.LVDS_17_P
MSIO150NBS	F2	SLOT8.LVDS_1_N
MSIO150PB8	E1	SLOT8.LVDS_1_P
MSIO151NBS	I5	SLOT8.LVDS_2_N
MSIO151PB8	I4	SLOT8.LVDS_2_P
MSIO152NBS	K4	SLOT8.LVDS_3_N
MSIO152PB8	M6	SLOT8.LVDS_3_P
MSIO153NBS	M7	SLOT8.LVDS_4_N
MSIO153PB8	G2	SLOT8.LVDS_5_N
MSIO154NBS	G1	SLOT8.LVDS_5_P
MSIO154PB8	P4	SLOT2.LVDS_0_N
MSIO156NBS	N4	SLOT2.LVDS_0_P
MSIO156PB8	N3	SLOT1.LVDS_0_N
MSIO157NBS	N6	SLOT1.LVDS_0_P
MSIO157PB8	M3	SLOT8.LVDS_6_N
MSIO158NBS	N7	SLOT8.LVDS_6_P
MSIO158PB8	N6	SLOT8.LVDS_7_N
MSIO159NBS	N9	SLOT8.LVDS_7_P
MSIO159PB8	N8	SLOT8.LVDS_8_N
MSIO160NBS	N2	SLOT8.LVDS_8_P
MSIO160PB8	M5	SLOT8.LVDS_9_N
MSIO161NBS	M2	SLOT8.LVDS_9_P
MSIO161PB8	M10	SLOT8.LVDS_10_N
MSIO163NBS	N10	SLOT8.LVDS_10_P
MSIO165NBS	P6	SLOT8.LVDS_11_N
MSIO165PB8	P7	SLOT8.LVDS_11_P
MSIO166NBS	J2	SLOT8.LVDS_12_N
MSIO166PB8	H1	SLOT8.LVDS_12_P
MSIO167NBS	J1	SLOT8.LVDS_13_N
MSIO167PB8	K1	SLOT8.LVDS_13_P
MSIO168NBS	P3	SLOT8.LVDS_14_N
MSIO168PB8	R4	SLOT8.LVDS_14_P
MSIO169NBS	M1	SLOT8.LVDS_15_N
MSIO169PB8	N1	SLOT8.LVDS_15_P
MSIO170NBS	P2	SLOT8.LVDS_16_N
MSIO170PB8	R3	SLOT8.LVDS_16_P
MSIO172NBS	P1	SLOT8.LVDS_17_N
MSIO172PB8	R1	SLOT8.LVDS_17_P

Project/Equipment DI/OT

Document BE/CO

CERN

DI/OT Rad-tol System Board
FPGA I/O Banks B0, B3

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXXX-VX-X

Sheet 6 of 17

Designer C.Gentos

Drawn by C.Gentos

Check by *

Last Mod. C.Gentos

Print Date 16/11/2020 16:33:31

Size Rev A3 * 5

Caution on pin-swapping: the S0_P pins are connected to Global I/O pins to be able to drive FPGA clocks and can't be swapped with other peripheral I/Os.
 Boards 1-3 can drive global buffers directly or use CCC blocks;
 Boards 4-6 can drive global buffers directly or through VCCC crossbars; and
 Boards 7-8 can only reach global buffers through CCC blocks.

IC1A M2GL090T-FGG6761

BANK 0

MSIO111NB0	J12	SLOT1.LVDS_1_N
MSIO111PB0	J11	SLOT1.LVDS_1_P
MSIO112NB0	A9	SLOT1.LVDS_2_N
MSIO112PB0	A8	SLOT1.LVDS_2_P
MSIO113NB0	A10	SLOT1.LVDS_3_N
MSIO113PB0	A9	SLOT1.LVDS_3_P
MSIO114NB0	A8	SLOT1.LVDS_4_N
MSIO114PB0	A7	SLOT1.LVDS_4_P
MSIO115NB0	A9	SLOT1.LVDS_5_N
MSIO115PB0	A8	SLOT1.LVDS_5_P
MSIO116NB0	A7	SLOT1.LVDS_6_N
MSIO116PB0	A6	SLOT1.LVDS_6_P
MSIO117NB0	A5	SLOT1.LVDS_7_N
MSIO117PB0	A4	SLOT1.LVDS_7_P
MSIO118NB0	A3	SLOT1.LVDS_8_N
MSIO118PB0	A2	SLOT1.LVDS_8_P
MSIO119NB0	A1	SLOT1.LVDS_9_N
MSIO119PB0	A0	SLOT1.LVDS_9_P
MSIO120NB0	A4	SLOT1.LVDS_10_N
MSIO120PB0	A3	SLOT1.LVDS_10_P
MSIO121NB0	F7	SLOT1.LVDS_11_N
MSIO121PB0	F8	SLOT1.LVDS_11_P
MSIO122NB0	B7	SLOT1.LVDS_12_N
MSIO122PB0	B6	SLOT1.LVDS_12_P
MSIO123NB0	C5	SLOT1.LVDS_13_N
MSIO123PB0	C4	SLOT1.LVDS_13_P
MSIO124NB0	D7	SLOT1.LVDS_14_N
MSIO124PB0	D6	SLOT1.LVDS_14_P
MSIO125NB0	E6	SLOT1.LVDS_15_N
MSIO125PB0	E7	SLOT1.LVDS_15_P

BANK 3

MSIO00NB3	W22	SLOT1.LVDS_16_N
MSIO00PB3	W21	SLOT1.LVDS_16_P
MSIO10NB3	A22	SLOT1.LVDS_17_N
MSIO10PB3	A23	SLOT1.LVDS_17_P
MSIO11NB3	A25	SLOT2.LVDS_1_N
MSIO11PB3	A24	SLOT2.LVDS_1_P
MSIO12NB3	A21	SLOT2.LVDS_2_N
MSIO12PB3	A20	SLOT2.LVDS_2_P
MSIO13NB3	V20	SLOT2.LVDS_3_N
MSIO13PB3	C22	SLOT2.LVDS_3_P
MSIO14NB3	A26	SLOT2.LVDS_4_N
MSIO14PB3	A25	SLOT2.LVDS_4_P
MSIO15NB3	V24	SLOT2.LVDS_5_N
MSIO15PB3	V23	SLOT2.LVDS_5_P
MSIO16NB3	V22	SLOT2.LVDS_6_N
MSIO16PB3	V21	SLOT2.LVDS_6_P
MSIO17NB3	V24	SLOT2.LVDS_7_N
MSIO17PB3	V23	SLOT2.LVDS_7_P
MSIO18NB3	V25	SLOT2.LVDS_8_N
MSIO18PB3	V24	SLOT2.LVDS_8_P
MSIO19NB3	V26	SLOT2.LVDS_9_N
MSIO19PB3	V25	SLOT2.LVDS_9_P
MSIO20NB3	GB13	SLOT2.LVDS_10_N
MSIO20PB3	GB9	SLOT2.LVDS_10_P
MSIO21NB3	CC1	SLOT2.LVDS_11_N
MSIO21PB3	CC0	SLOT2.LVDS_11_P
MSIO22NB3	CC2	SLOT2.LVDS_12_N
MSIO22PB3	CC1	SLOT2.LVDS_12_P
MSIO23NB3	CC3	SLOT2.LVDS_13_N
MSIO23PB3	CC2	SLOT2.LVDS_13_P
MSIO24NB3	CC4	SLOT2.LVDS_14_N
MSIO24PB3	CC3	SLOT2.LVDS_14_P
MSIO25NB3	CC5	SLOT2.LVDS_15_N
MSIO25PB3	CC4	SLOT2.LVDS_15_P
MSIO26NB3	CC1	SLOT2.LVDS_16_N
MSIO26PB3	CC0	SLOT2.LVDS_16_P
MSIO27NB3	CC6	SLOT2.LVDS_17_N
MSIO27PB3	CC5	SLOT2.LVDS_17_P
MSIO28NB3	CC7	SLOT2.LVDS_18_N
MSIO28PB3	CC6	SLOT2.LVDS_18_P
MSIO29NB3	CC8	SLOT2.LVDS_19_N
MSIO29PB3	CC7	SLOT2.LVDS_19_P
MSIO30NB3	CC9	SLOT2.LVDS_20_N
MSIO30PB3	CC8	SLOT2.LVDS_20_P
MSIO31NB3	CC10	SLOT2.LVDS_21_N
MSIO31PB3	CC9	SLOT2.LVDS_21_P
MSIO32NB3	CC11	SLOT2.LVDS_22_N
MSIO32PB3	CC10	SLOT2.LVDS_22_P
MSIO33NB3	CC12	SLOT2.LVDS_23_N
MSIO33PB3	CC11	SLOT2.LVDS_23_P
MSIO34NB3	CC13	SLOT2.LVDS_24_N
MSIO34PB3	CC12	SLOT2.LVDS_24_P
MSIO35NB3	CC14	SLOT2.LVDS_25_N
MSIO35PB3	CC13	SLOT2.LVDS_25_P
MSIO36NB3	CC15	SLOT2.LVDS_26_N
MSIO36PB3	CC14	SLOT2.LVDS_26_P
MSIO37NB3	CC16	SLOT2.LVDS_27_N
MSIO37PB3	CC15	SLOT2.LVDS_27_P
MSIO38NB3	CC17	SLOT2.LVDS_28_N
MSIO38PB3	CC16	SLOT2.LVDS_28_P
MSIO39NB3	CC18	SLOT2.LVDS_29_N
MSIO39PB3	CC17	SLOT2.LVDS_29_P
MSIO40NB3	CC19	SLOT2.LVDS_30_N
MSIO40PB3	CC18	SLOT2.LVDS_30_P
MSIO41NB3	CC20	SLOT2.LVDS_31_N
MSIO41PB3	CC19	SLOT2.LVDS_31_P
MSIO42NB3	CC21	SLOT2.LVDS_32_N
MSIO42PB3	CC20	SLOT2.LVDS_32_P
MSIO43NB3	CC22	SLOT2.LVDS_33_N
MSIO43PB3	CC21	SLOT2.LVDS_33_P
MSIO44NB3	CC23	SLOT2.LVDS_34_N
MSIO44PB3	CC22	SLOT2.LVDS_34_P
MSIO45NB3	CC24	SLOT2.LVDS_35_N
MSIO45PB3	CC23	SLOT2.LVDS_35_P
MSIO46NB3	CC25	SLOT2.LVDS_36_N
MSIO46PB3	CC24	SLOT2.LVDS_36_P
MSIO47NB3	CC26	SLOT2.LVDS_37_N
MSIO47PB3	CC25	SLOT2.LVDS_37_P
MSIO48NB3	CC27	SLOT2.LVDS_38_N
MSIO48PB3	CC26	SLOT2.LVDS_38_P
MSIO49NB3	CC28	SLOT2.LVDS_39_N
MSIO49PB3	CC27	SLOT2.LVDS_39_P
MSIO50NB3	CC29	SLOT2.LVDS_40_N
MSIO50PB3	CC28	SLOT2.LVDS_40_P

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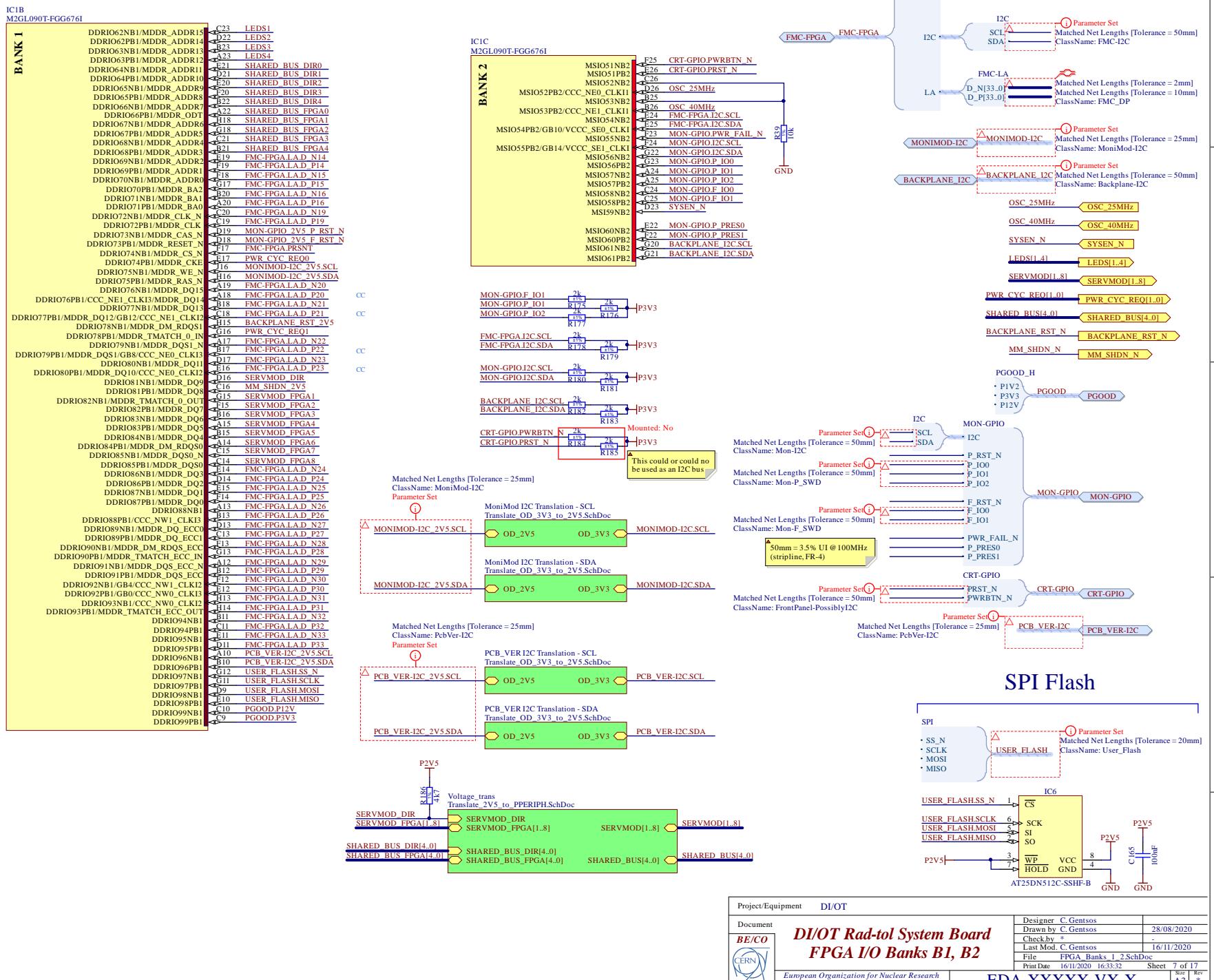
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Source location: <https://www.ohwr.org/project/diot-sb-ig>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

Bank 1 powered by 2.5V, Bank 2 by 3.3V



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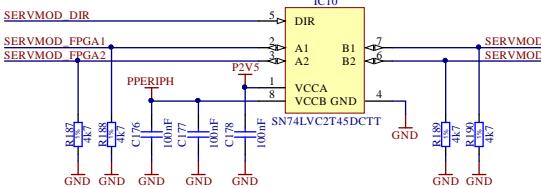
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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Maybe that's nit-picking but according to the datasheet, VCCB must be ramped-up with or after VCCA. If VCCB is set to 3V3 its ramp-up will come just slightly ahead of VCCA but not by much.



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A

B

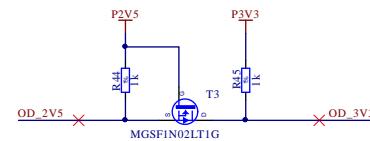
C

D

E

Level translators for open-drain interfaces as described in AN10441

OD_2V5 OD_2V5
OD_3V3 OD_3V3



Project/Equipment	DI/OT	
Document	Designer <u>C.Gentos</u>	06/10/2020
BE/CO	Drawn by <u>C.Gentos</u>	
	Check by *	
	Last Mod. <u>C.Gentos</u>	11/11/2020
	File <u>Translate OD_3V3 to 2V5.SchDoc</u>	
	Print Date <u>16/11/2020 16:33:33</u>	Sheet <u>9 of 17</u>
	European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland	Size <u>A3</u> Rev <u>*</u>
	DI/OT Rad-tol System Board Open-drain Voltage Translators	
	EDA-XXXXX-VX-X	

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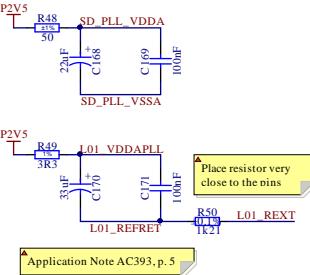
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

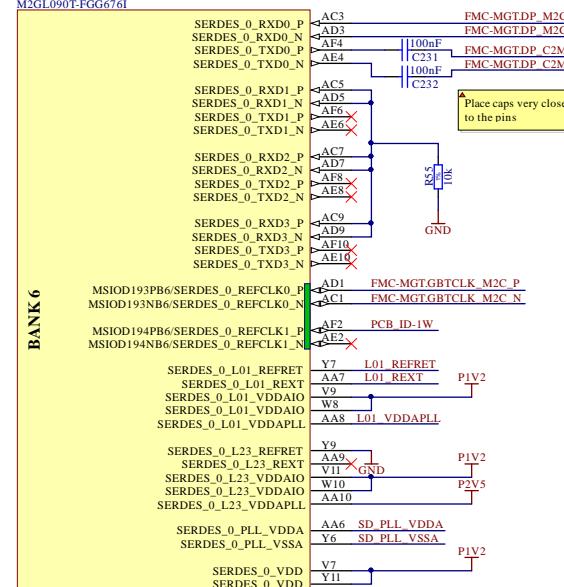
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Banks powered by 2.5V

SerDes PLL RC filters

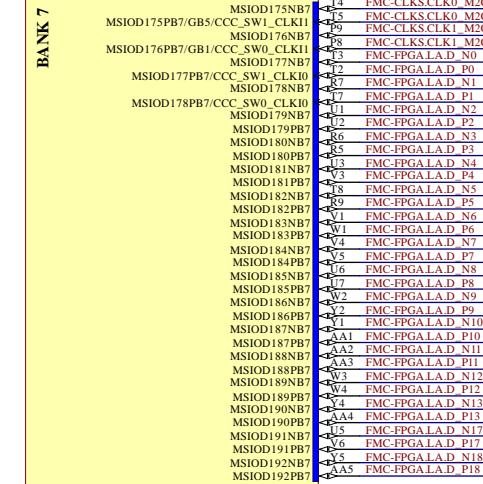


IC1H
M2GL090T-FGG676I

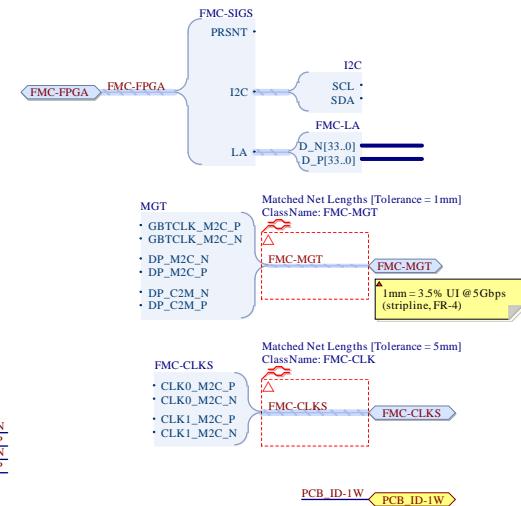


BANK 6

IC1F
M2GL090T-FGG676I



BANK 7



Project/Equipment DI/OT

Document BE/CO



DI/OT Rad-tol System Board
FPGA I/O Banks B6, B7

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXXX-VX-X

Designer	C.Gentos	28/08/2020
Drawn by	C.Gentos	-
Check by	*	-
Last Mod.	C.Gentos	16/11/2020
File	FPGA_Banks_6_7.SchDoc	
Print Date	16/11/2020 16:33:33	Sheet 10 of 17
Size	A3	Rev *

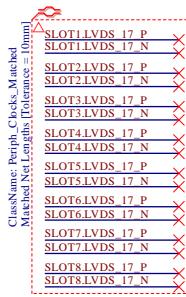
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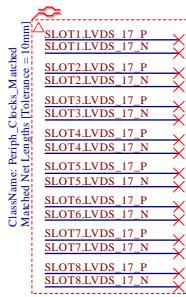
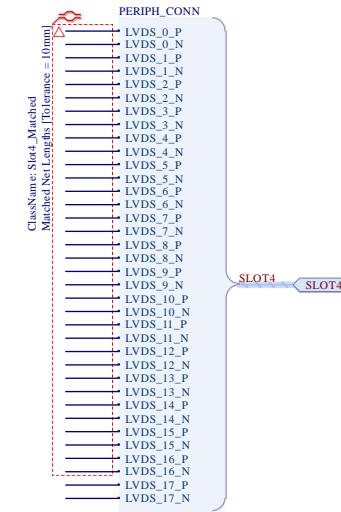
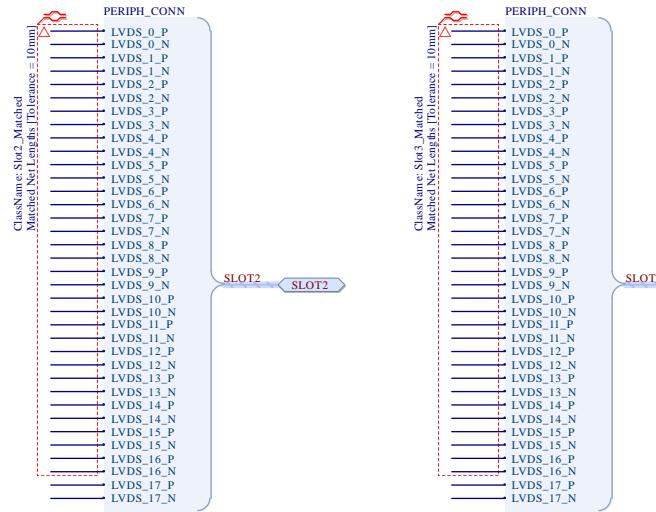
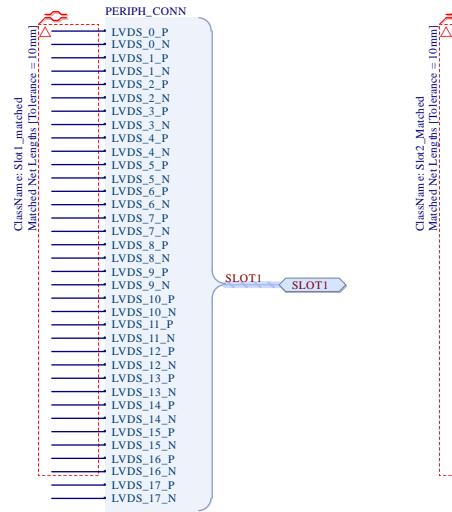
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

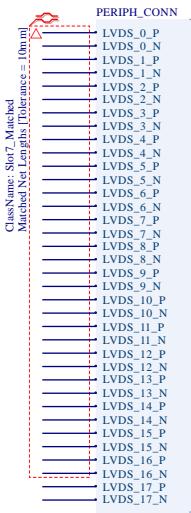
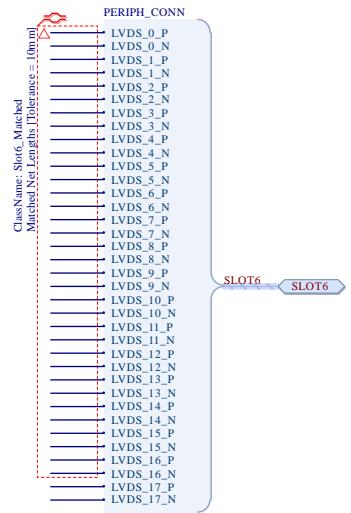
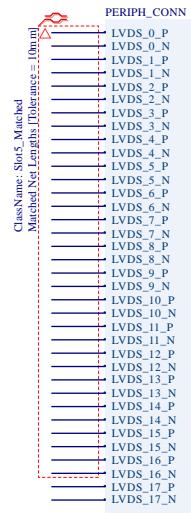
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The clock-capable pairs are length-matched between the different peripheral boards, instead



The clock-capable pairs are length-matched between the different peripheral boards, instead



Project/Equipment DI/OT

Document

BE/CO



**DI/OT Rad-tol System Board
Constrain Periph. Board Signals**

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

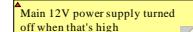
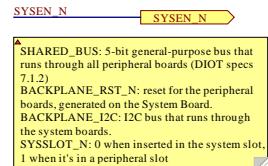
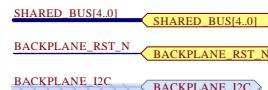
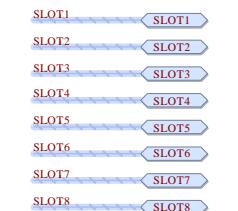
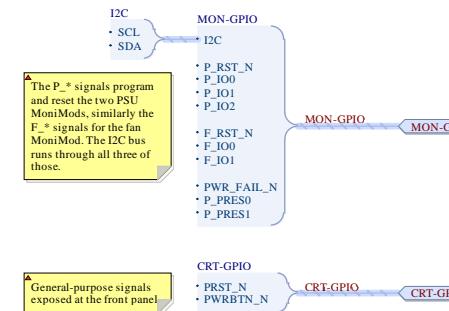
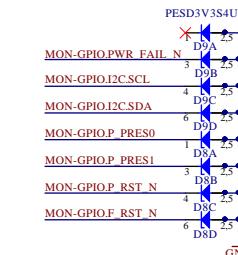
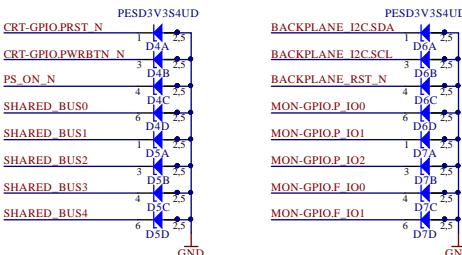
Designer: C. Gentos	09/10/2020
Drawn by: C. Gentos	-
Check-by:	-
Last Mod.: C. Gentos	16/11/2020
File: Constrain_Periph_Nets.SchDoc	
Print Date: 16/11/2020 16:33:33	Sheet: 11 of 17
Size: A3	Rev: *

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All the nets that are exposed to the front panel, the power backplane, or that run through all the peripheral boards, are protected

A

B

C

D

E

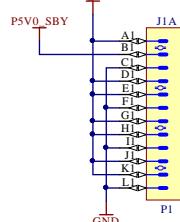
A

B

C

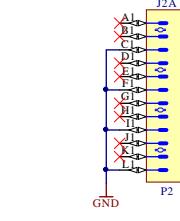
D

E



Backplane grounds L2 at the system slot, leaves it open at the peripheral slots. Sensing that we can still where we're plugged in.

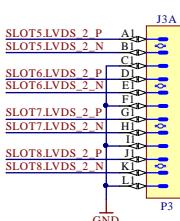
P1 Connector



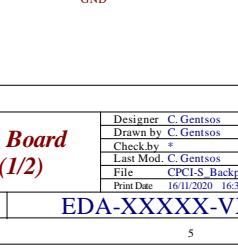
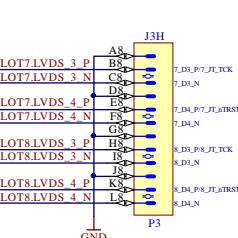
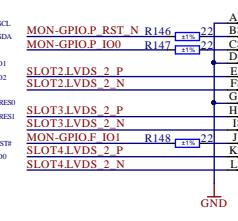
<slot>_JT * JTAG functionality is enabled when a peripheral board is in service mode

<slot>_MTX / <slot>_MRX signals can be connected to MGT transceivers on the non-rad-tol system board

P2 Connector



P3 Connector



Project/Equipment DI/OT

Document DI/OT Rad-tol System Board CPCI-S Backplane (1/2)

BE/CO CERN

Designer C. Gantos

Drawn by C. Gantos

Check by *

Last Mod. 11/2020

File CPCI-S Backplane PI-P3.SchDoc

Date 16/11/2020 16:33:34 Sheet 12 of 17

Size A3 Rev *

European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland

EDA-XXXXXX-VX-X

A3 Rev *

1

2

3

4

5

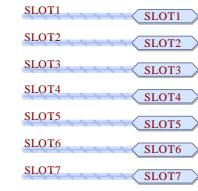
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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SERVMOD1[1..8] ————— SERVMOD2[1..8]

A

B

C

D

E

A

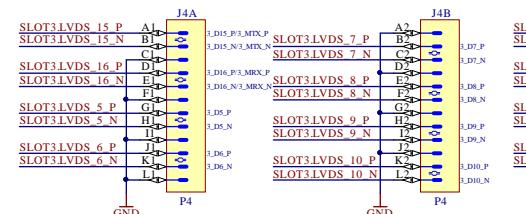
B

C

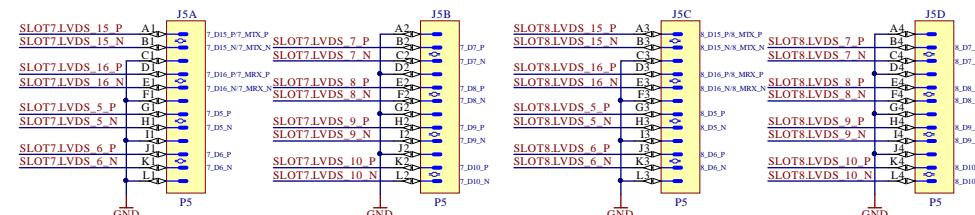
D

E

P4 Connector



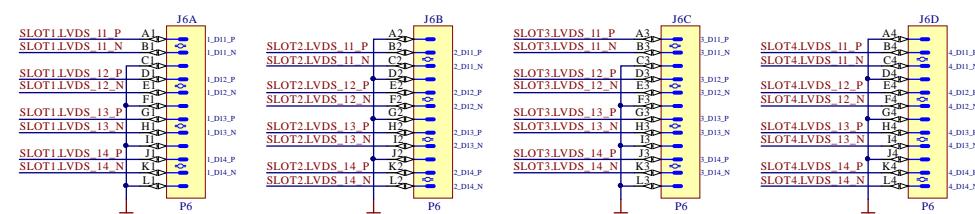
P5 Connector



n_PE_CLK diff pairs will provide low-noise, high-quality clocks to the peripheral boards (2.1.7)

The DECT_RIO (A8) and DECT_BPR (D8) pins are connected to GND in the DI/OT backplane, they're not necessarily GND in the backplanes. As they're not used, they're left unconnected to improve compatibility.

P6 Connector



Project/Equipment DI/OT

Document BE/CO



DI/OT Rad-tol System Board
CPCI-S Backplane (2/2)

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXXX-VX-X

Size Rev
A3 * 13 of 17

Designer: C. Gentos Drawn by: C. Gentos 28/08/2020

Check by: * Last Mod: C. Gentos 11/11/2020

File: CPCIS-Backplane_P4-P6.SchDoc Print Date: 16/11/2020 16:33:36 Sheet: 13 of 17

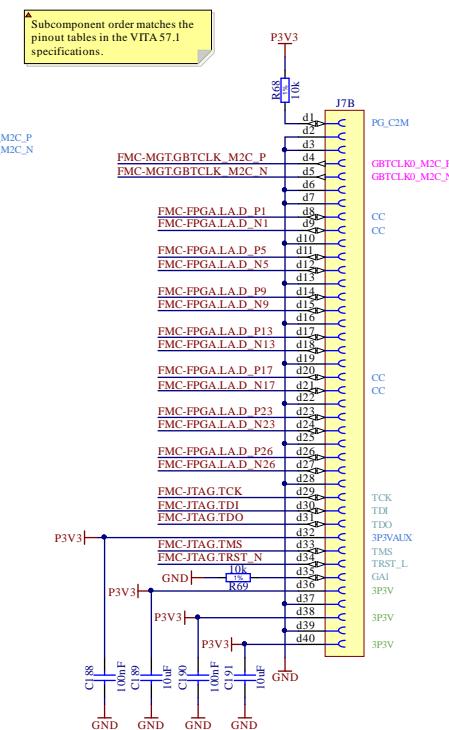
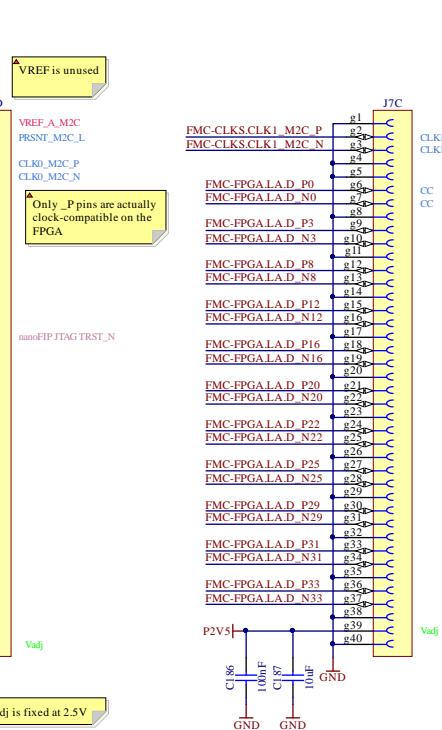
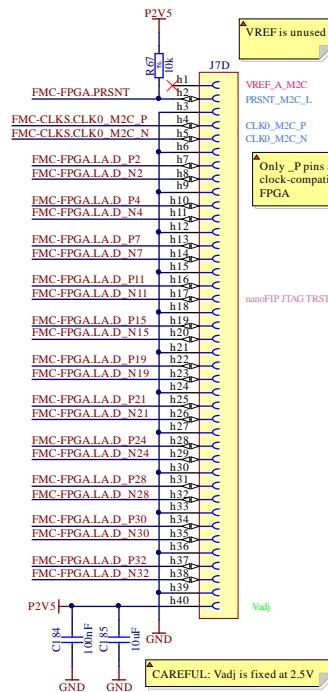
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

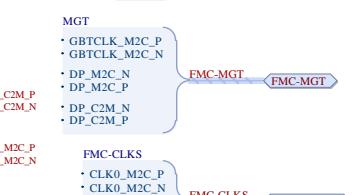
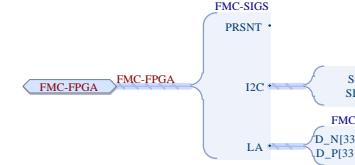
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Mounting holes



Project/Equipment	DI/OT	Document	BE/CO	DI/OT Rad-tol System Board FMC	Print Date	Sheet	Size	Rev
					16/11/2020 16:33:36	14 of 17	A3	*
					European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		EDA-XXXXXX-VX-X	



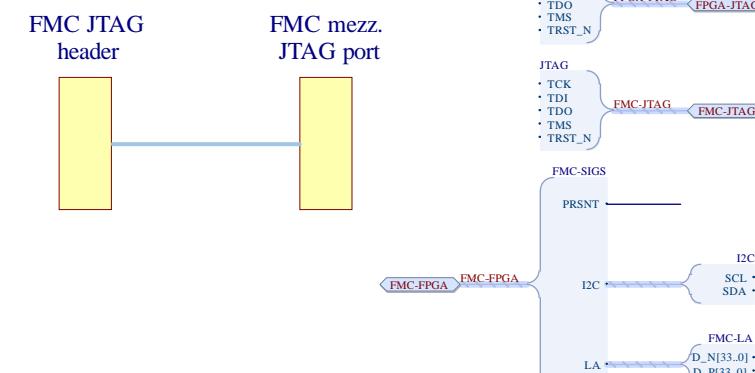
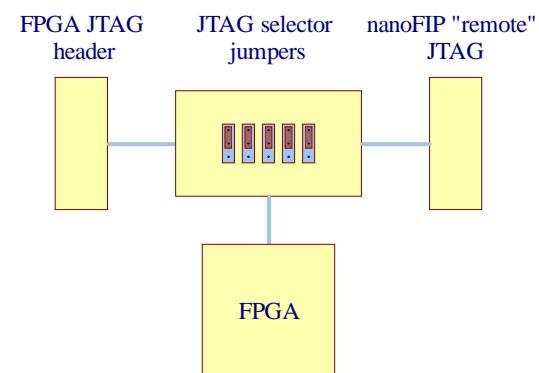
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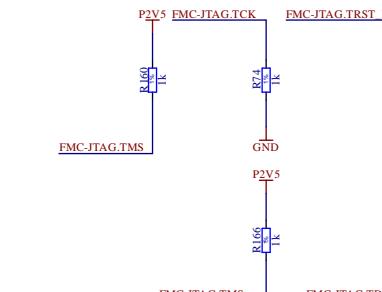
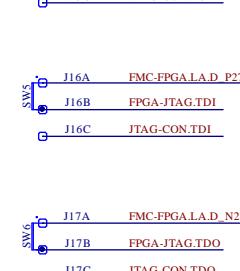
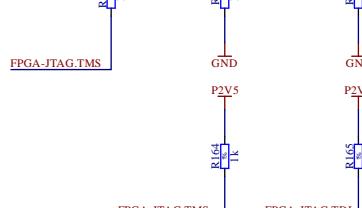
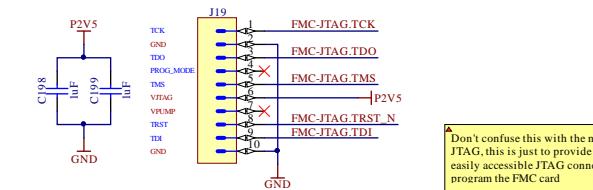
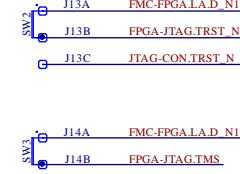
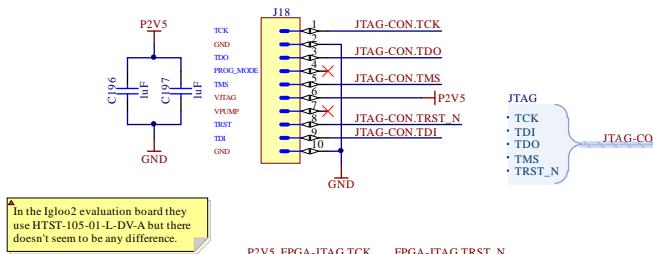
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FPGA JTAG header

FPGA JTAG selector

FMC JTAG header



Project/Equipment	DI/OT
Document	DI/OT Rad-tol System Board JTAG Chains
BE/CO	CERN
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland	EDA-XXXXX-VX-X
Print Date: 16/11/2020 16:33:37	Sheet 15 of 17
Size: A3	Rev: *

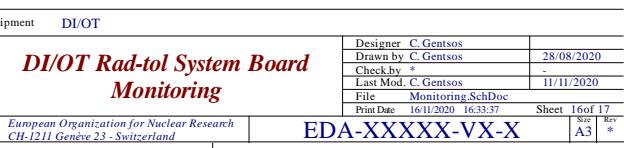
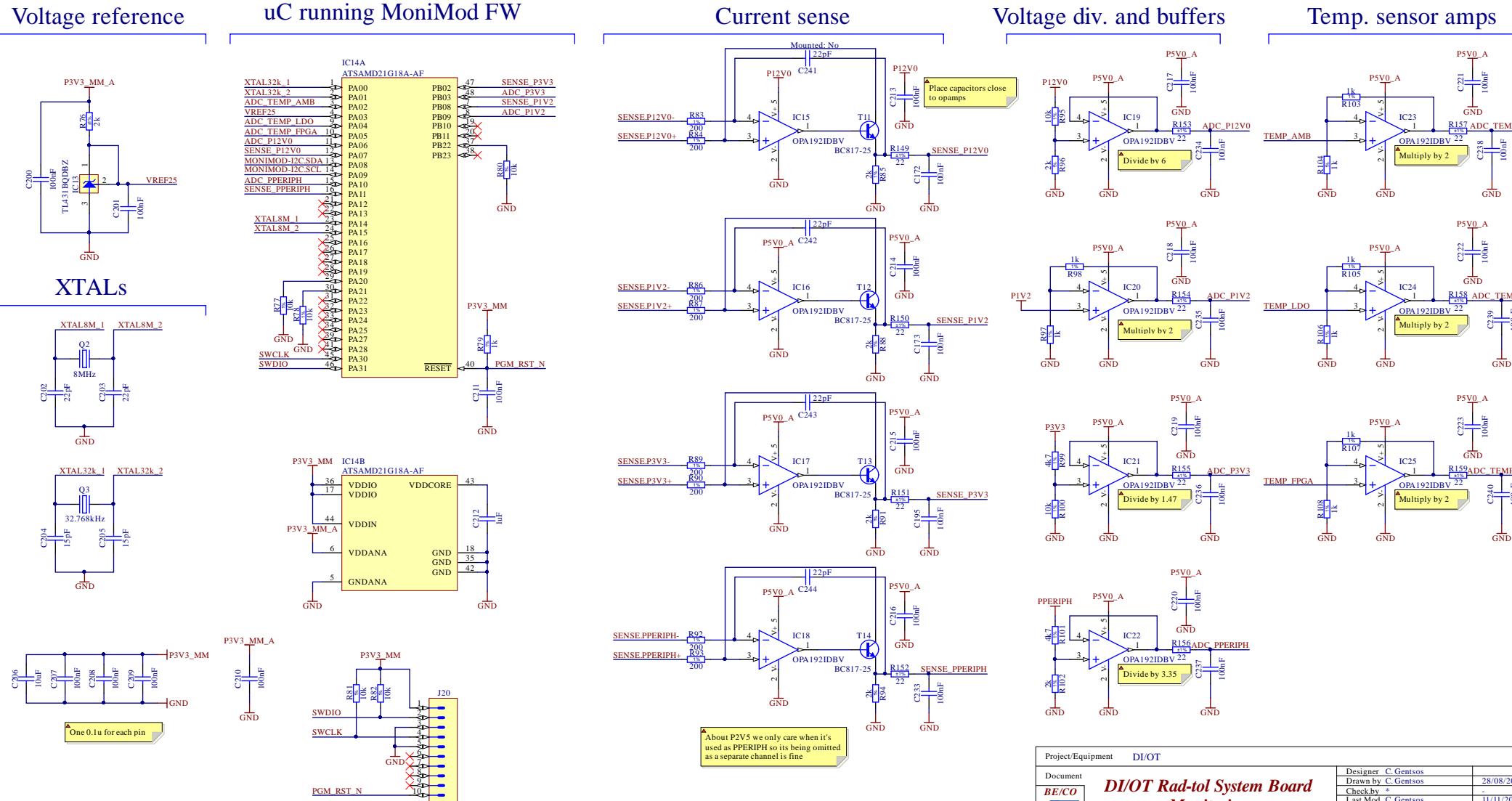
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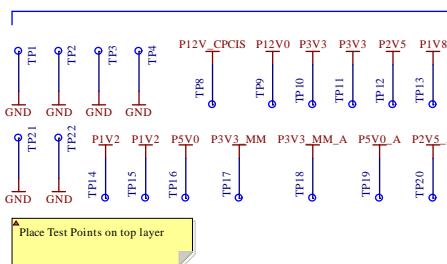
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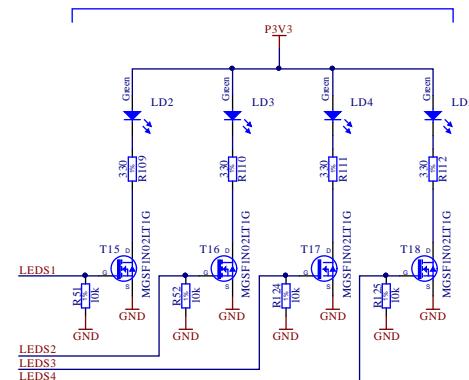
Source location: <https://www.ohwr.org/project/diot-sb-ig1>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board [PCB] or other product you make using this documentation.

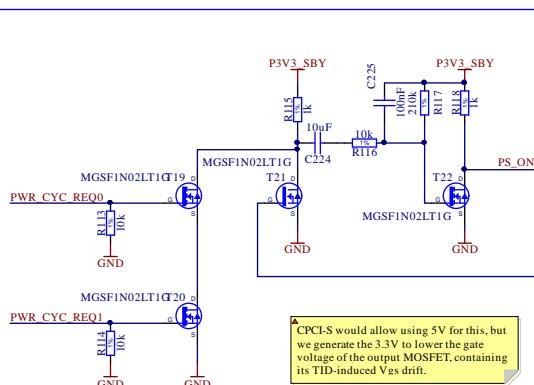
Power rail test points



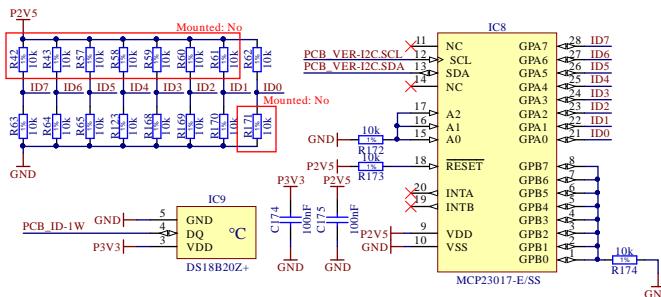
User LEDs



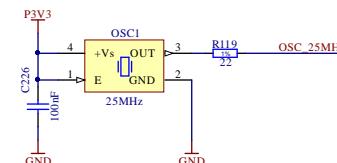
Power cycle pulse generator



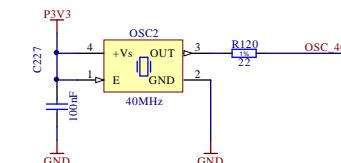
Board version encoding and ID



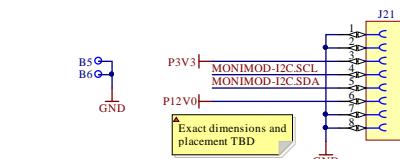
25MHz oscillator



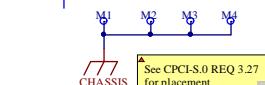
40MHz oscillator



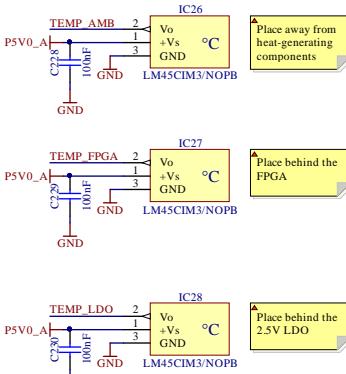
Expansion pin header



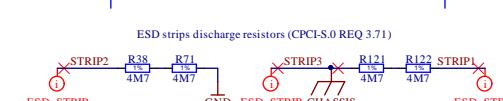
Front panel mounting holes



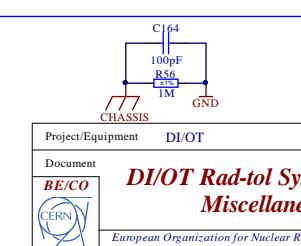
Temp sensors



ESD Protection



Chassis-GND connection



**DI/OT Rad-tol System Board
Miscellaneous**

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

Fiducials



Project/Equipment	DI/OT	Designer	C. Gentos	Date	28/08/2020
Document		Drawn by	C. Gentos	Check by	*
BE/CO		Last Mod.	C. Gentos	File	Top_Misc.SchDoc
			<th>Print Date</th> <td>16/11/2020 16:33:38</td>	Print Date	16/11/2020 16:33:38
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				A3	